

# N- and P-Channel 20 V (D-S) MOSFET

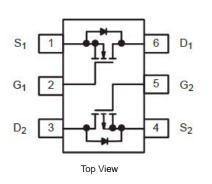
PRODUCT SUMMARY					
	V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω)	I <sub>D</sub> (A)		
N-Channel	20	0.270 at V <sub>GS</sub> = 4.5 V	0.60		
		0.410 at V <sub>GS</sub> = 2.5 V	0.55		
P-Channel	- 20	0.660 at V <sub>GS</sub> = - 4.5 V	- 0.30		
		0.840 at V <sub>GS</sub> = - 2.5 V	- 0.25		

#### **FEATURES**

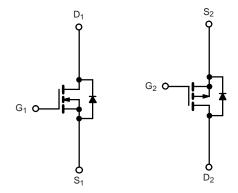
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
  Compliant to RoHS Directive 2002/95/EC



HALOGEN FREE Available



SC-75-6



N-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	<b>GS</b> T <sub>A</sub> = 25 °	°C, unless other	wise noted			
Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	- 20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	± 20		
	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	0.6	- 0.3		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 70 °C		0.55	- 0.25	•	
Pulsed Drain Current		I <sub>DM</sub>	3	- 2	A	
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		۱ <sub>S</sub>	1.05	- 1.05		
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 25 °C	PD	1.15		W	
	T <sub>A</sub> = 70 °C	FD 0.7		73	vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum handling to Anthing 13	t ≤ 5 s	P	93	110		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	R <sub>thJA</sub>	130	150	°C/W	
Maximum Junction-to-Lead	Steady State	R <sub>thJL</sub>	75	90		

Notes:

a. Surface Mounted on FR4 board.

b. t ≤ 5 s.



<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit			
Static	Cymbol	Test conditions			136.	Max.	Unit			
Gate Threshold Voltage		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA N-Ch		0.7						
	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	P-Ch	- 0.8			V			
			N-Ch			± 100	<u> </u>			
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V	P-Ch			± 100	nA			
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1	μA			
		V <sub>DS</sub> = - 24 V, V <sub>GS</sub> = 0 V	P-Ch			- 1				
		$V_{DS} = 24 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$	N-Ch			5				
		$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$	P-Ch			- 5				
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	N-Ch	3.7			_			
		V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	P-Ch	- 3			A			
		$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 0.6 \text{ A}$	N-Ch		0.410		Ω			
	Б	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 0.3A	P-Ch		0.840					
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 0.6 \text{ A}$	N-Ch		0.270					
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.3 A	P-Ch		0.660					
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	N-Ch		4.3		s			
		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 1.8 A	P-Ch		2.4					
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 1.05 A, V <sub>GS</sub> = 0 V	N-Ch		0.81	1.10	V			
		I <sub>S</sub> = - 1.05 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.83	- 1.10				
Dynamic <sup>b</sup>	•	•			•					
Total Gate Charge	0		N-Ch		2.1	3.2	nC			
Iotal Gate Charge	Qg	N-Channel V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 5 V, I <sub>D</sub> = 1.8 A	P-Ch		2.4	3.6				
Gate-Source Charge Gate-Drain Charge	Q <sub>gs</sub> Q <sub>gd</sub>	$v_{\rm DS} = 10$ v, $v_{\rm GS} = 0$ v, $i_{\rm D} = 1.0$ A	N-Ch		0.7					
		P-Channel	P-Ch		0.9					
		$V_{DS} = -15 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -1.8 \text{ A}$	N-Ch		0.7					
			P-Ch N-Ch	0.5	0.8	2.4				
Gate Resistance	Rg		P-Ch	3		2.4 11	Ω			
			N-Ch	•	7	11				
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel	P-Ch		8	12				
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, \text{ R}_{L} = 15 \Omega$	N-Ch		9	14				
		$\text{I}_\text{D}\cong \text{1}$ A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 6 $\Omega$	P-Ch		12	18				
Turn-Off Delay Time Fall Time	t <sub>d(off)</sub>	P-Channel	N-Ch		13	20	ns			
		$V_{DD}$ = - 15 V, R <sub>L</sub> = 15 $\Omega$			12	18	113			
		$I_{D}\cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_{g}$ = 6 $\Omega$	N-Ch		5	8				
		I <sub>F</sub> = 1.05 A, dl/dt = 100 A/µs	P-Ch		7	11				
Source-Drain Reverse Recovery Time	t <sub>rr</sub>		N-Ch		35	60 60				
		I <sub>F</sub> = - 1.05 A, dl/dt = 100 A/μs	P-Ch		30	60	U			

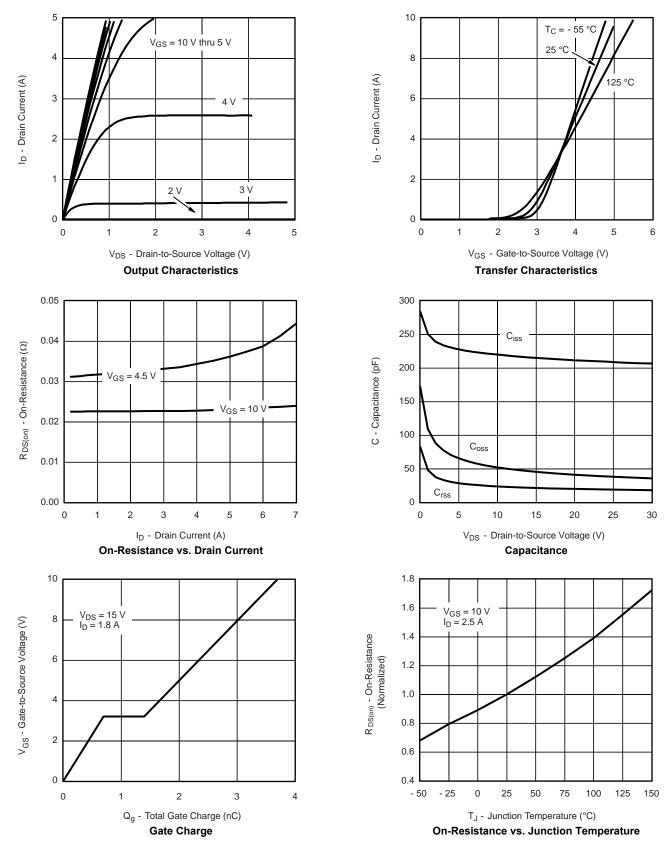
Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



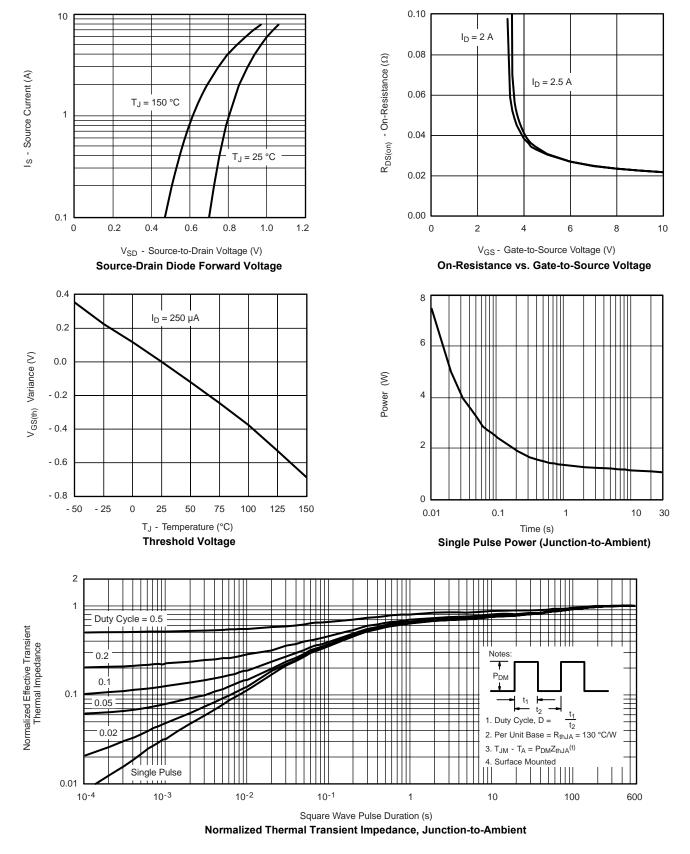
### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



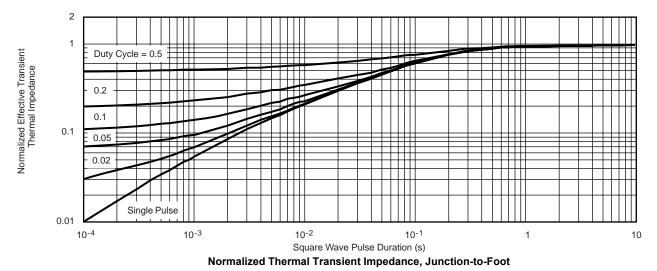
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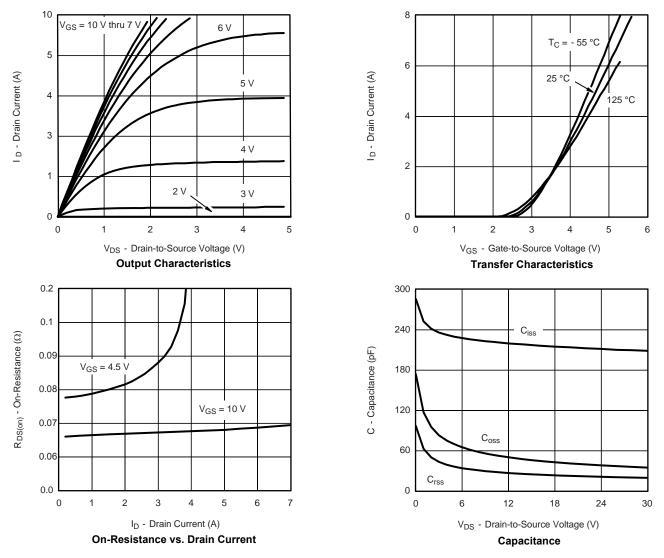






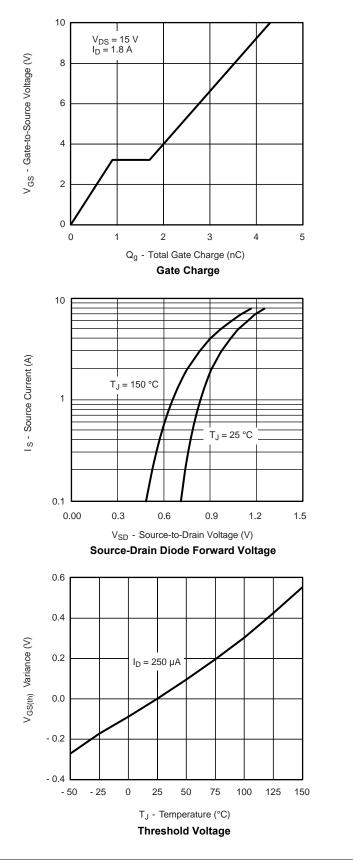
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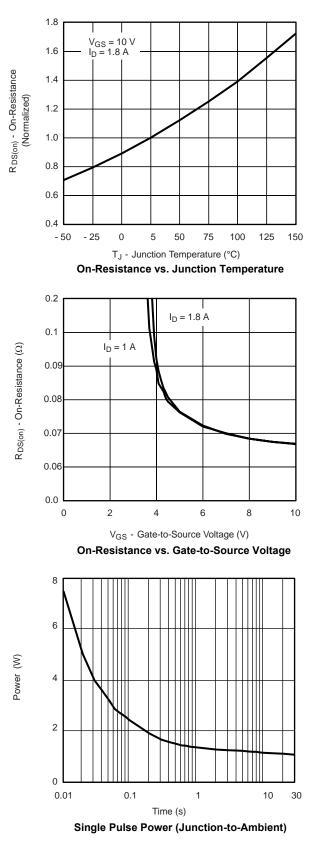




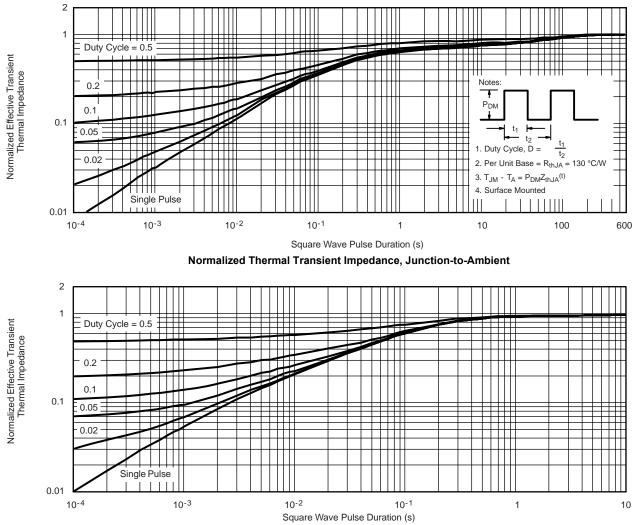


#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted









#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Normalized Thermal Transient Impedance, Junction-to-Foot



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